

Modeling Competitive Reactions and Heat Transfer Effects Applicable to Thermal Runaway in Lithium-Ion Batteries

Randy C. Shurtz, John C. Hewson

Fire Science and Technology, Sandia National Laboratories, Albuquerque, NM

Introduction

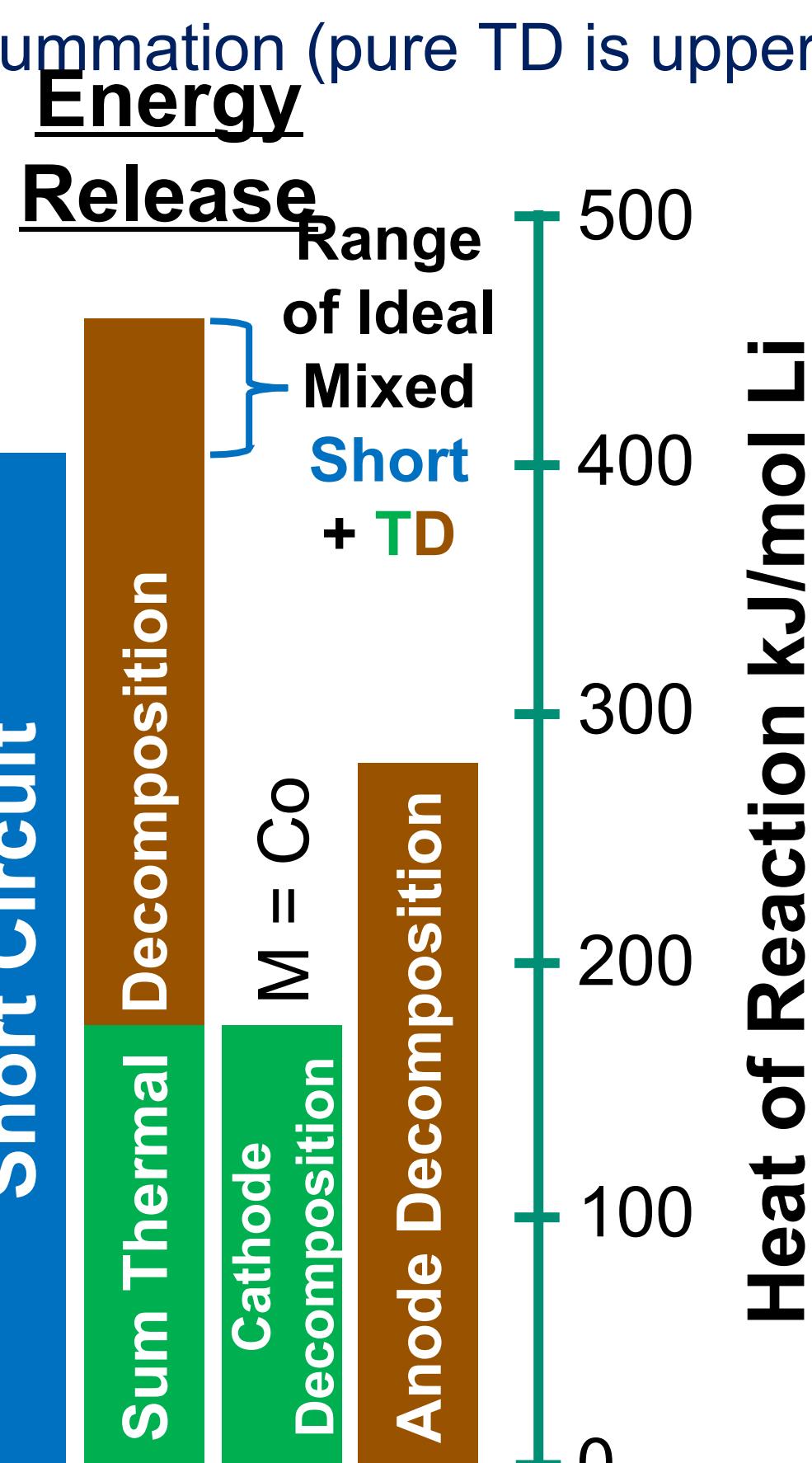
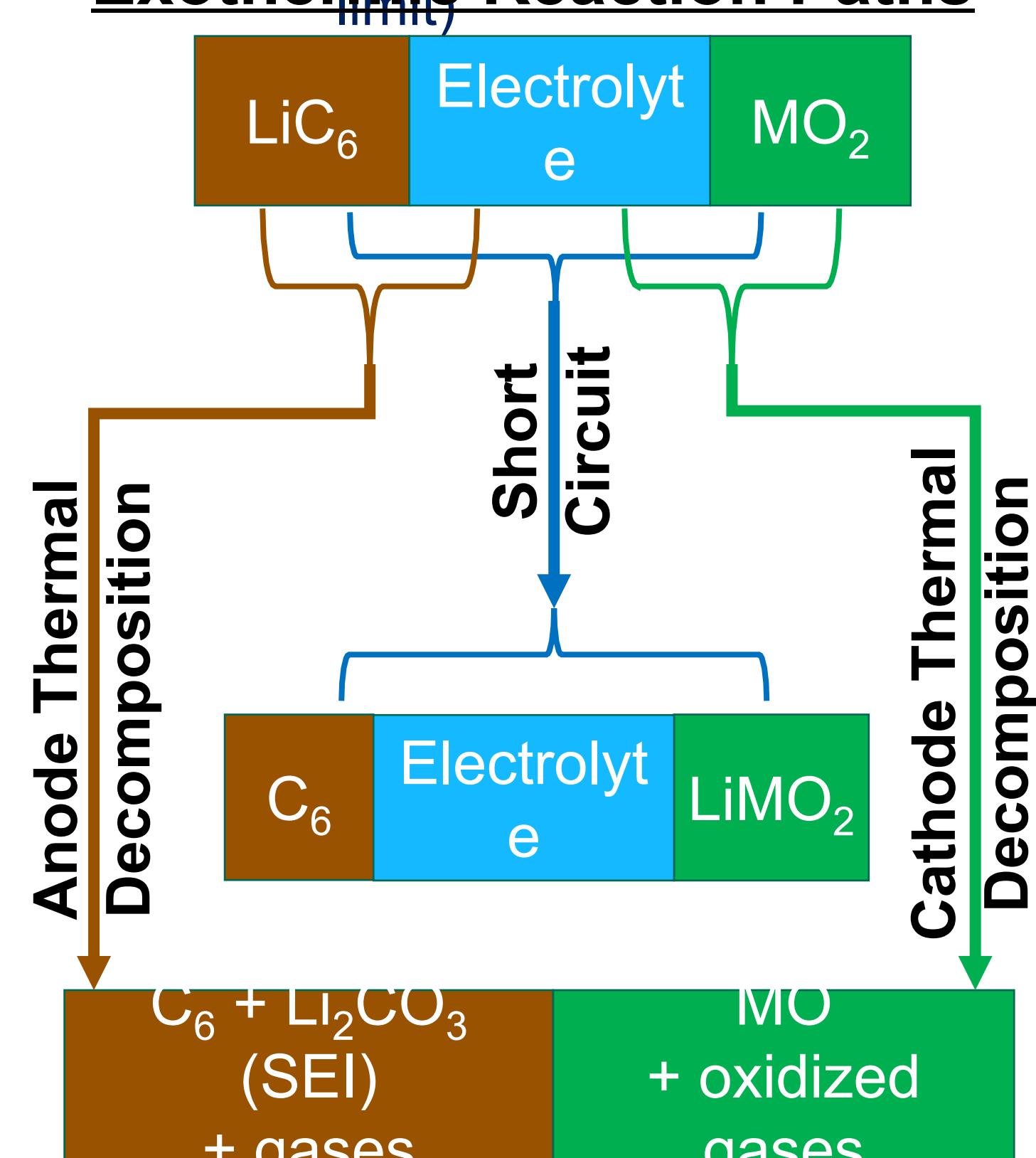
- Stationary energy storage systems (ESS) are increasingly deployed to maintain a robust and resilient grid.
- As system size increases, financial and safety issues become important topics.
- Holistic approach: electrochemistry, materials, and whole-cell abuse will fill knowledge gaps.
- Models enable knowledge to be applied to different scenarios and larger scales.

- When thermal runaway models include enough realistic physics, they can be used to:
 - Identify experimentally accessible parameters that strongly influence cascading propagation of thermal runaway through modules of cells.
 - Predict trends in heat transfer and cascading propagation behavior.
 - Identify regions of parameter space of greatest interest for experiments.

I: Competitive Energy Release Pathways

- Charged electrode species and organic electrolyte are reactive materials
 - Thermodynamically unstable
- Short circuits and thermal decomposition (TD) compete for common reactants
 - Total mixed heat release is not a summation (pure TD is upper limit)

Exothermic Reaction Paths



II: Effective Environment Temperature

- Evaluate mitigation strategies and explain novel experimental observations.
- Thermal runaway (TR) occurs when heat sources exceed heat dissipation losses

$$mc_p \frac{dT}{dt} = Q_{source} - \dot{Q}_{loss}, \text{ where } \dot{Q}_{loss} = hA(T - T_\infty) + \varepsilon\sigma A(T^4 - T_\infty^4)$$
- Energy sources driving thermal decomposition can be external or internal
- For internal source P , linearize losses and assume thermal equilibrium

$$\text{When } \frac{dT}{dt} = 0, Q_{source} = \dot{Q}_{loss}$$

If $\dot{Q}_{source} = P$ and \dot{Q}_{loss} is linearized as $\dot{Q}_{loss} = h_{eff}A(T - T_\infty)$,

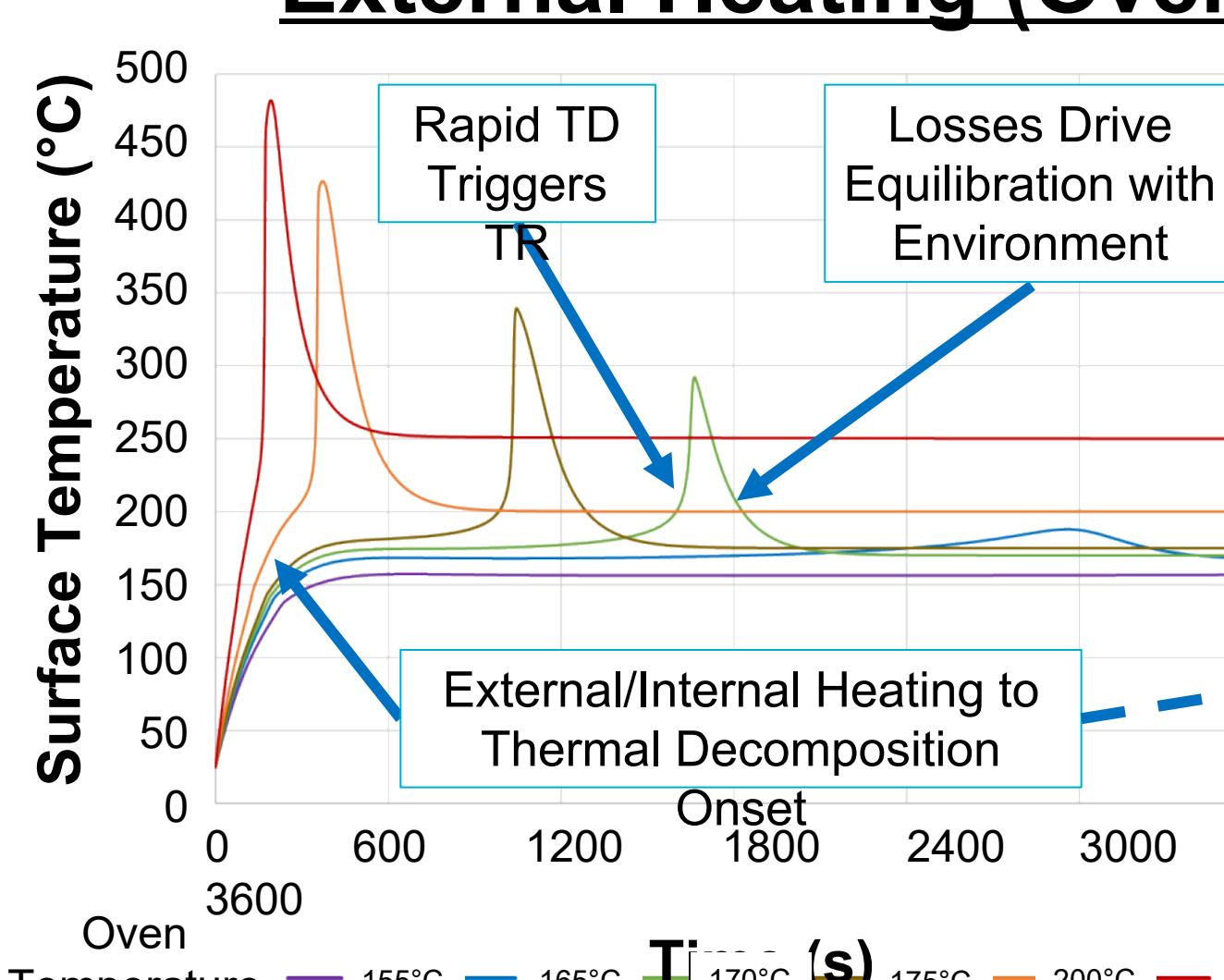
$$T_{eff} = T_\infty + P/h_{eff} A$$

Effective Environment Temperature

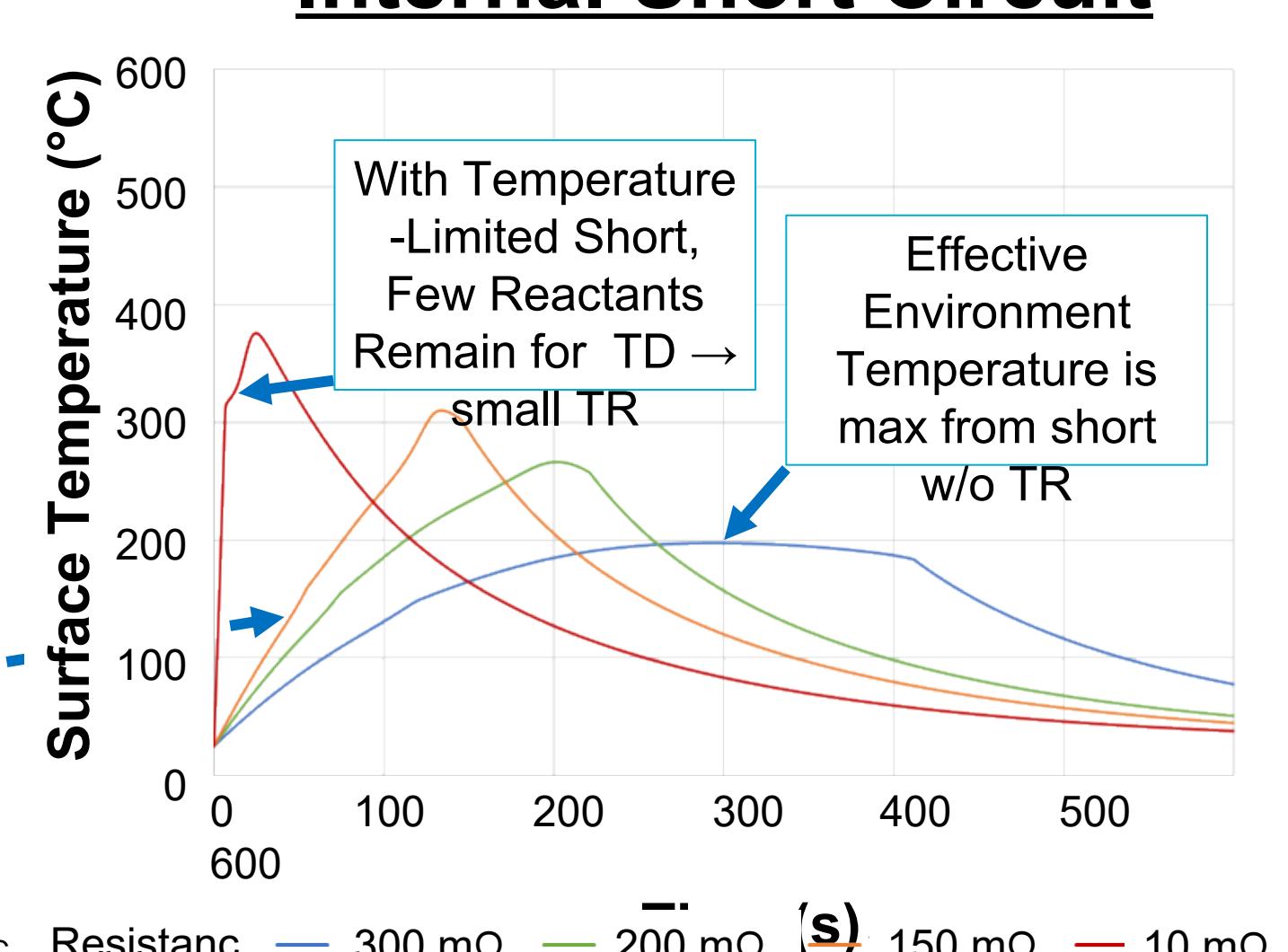
Derived

- Effective environment temperature is $T_{eff} = T_\infty + \frac{P}{h_{eff}A}$

External Heating (Oven)



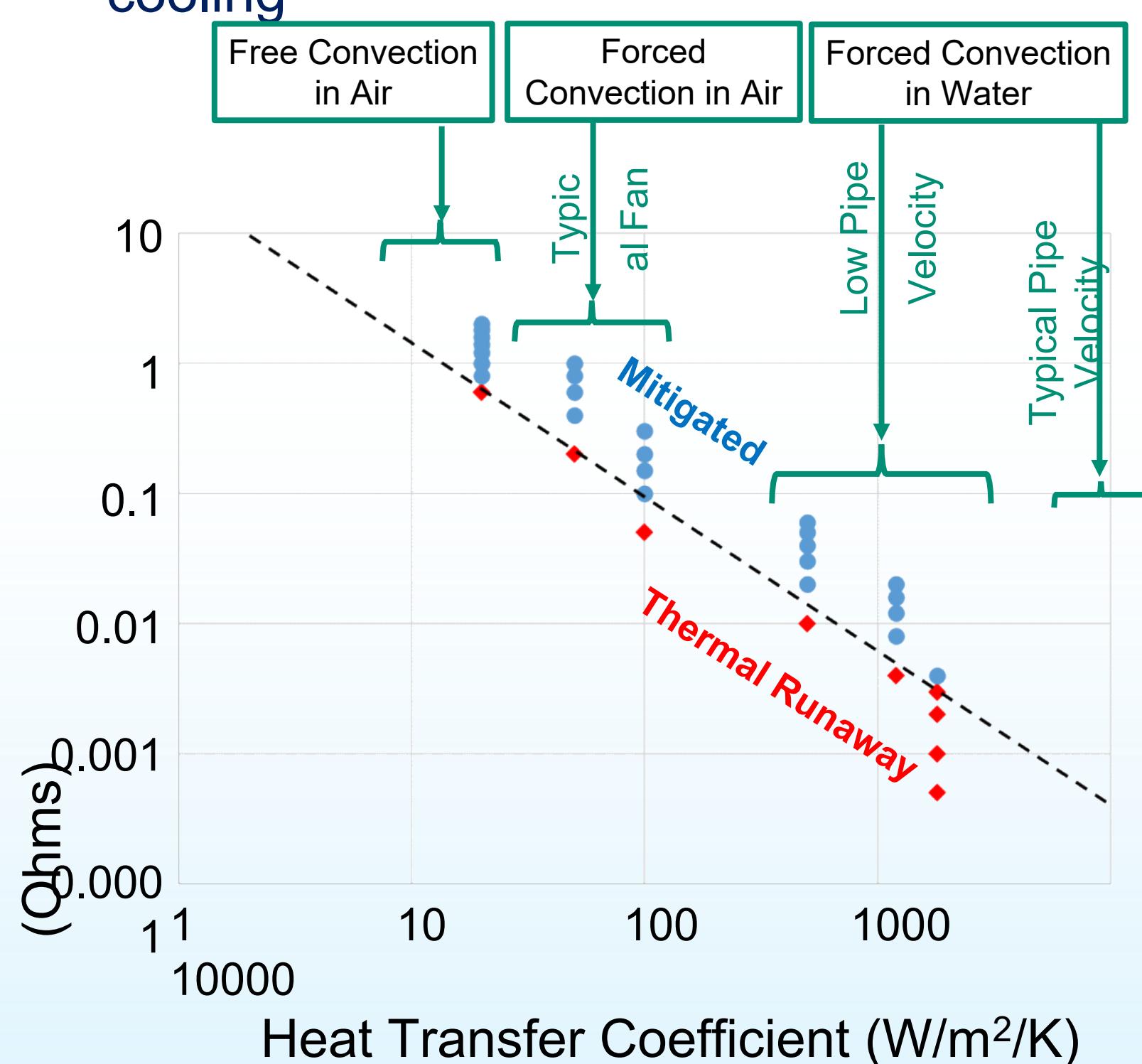
Internal Short Circuit



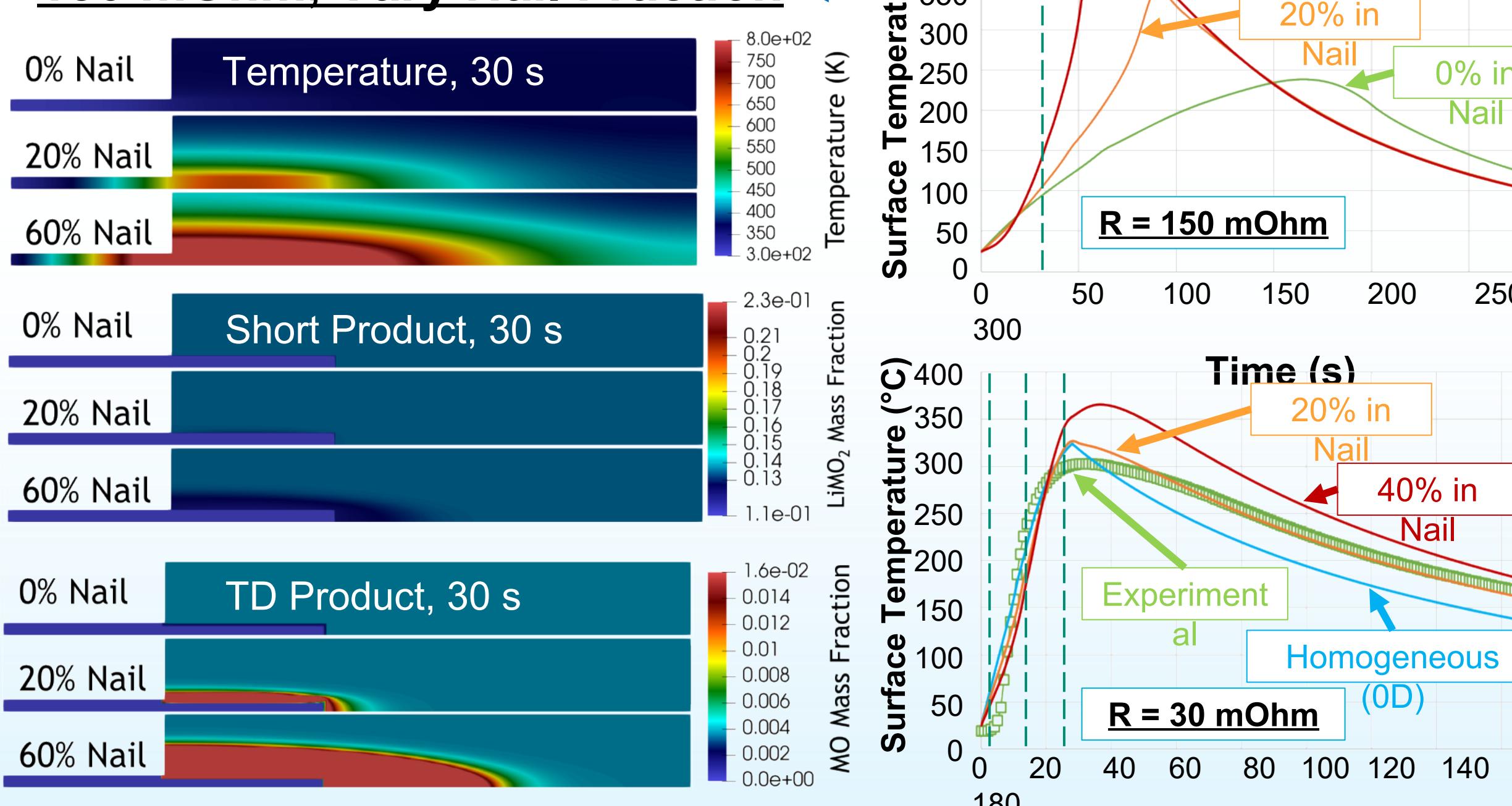
III: Cooling Requirements for Short Circuits

- Models can be used to estimate cooling requirements to mitigate TR
 - Homogeneous (0D) heating of 1.5 Ah 18650 shown at lower far left
 - Inhomogeneous deviations from 0D case shown at lower center + right
- Define power of short in effective environment temperature to correlate minimum internal short resistance that can be mitigated with degree of cooling

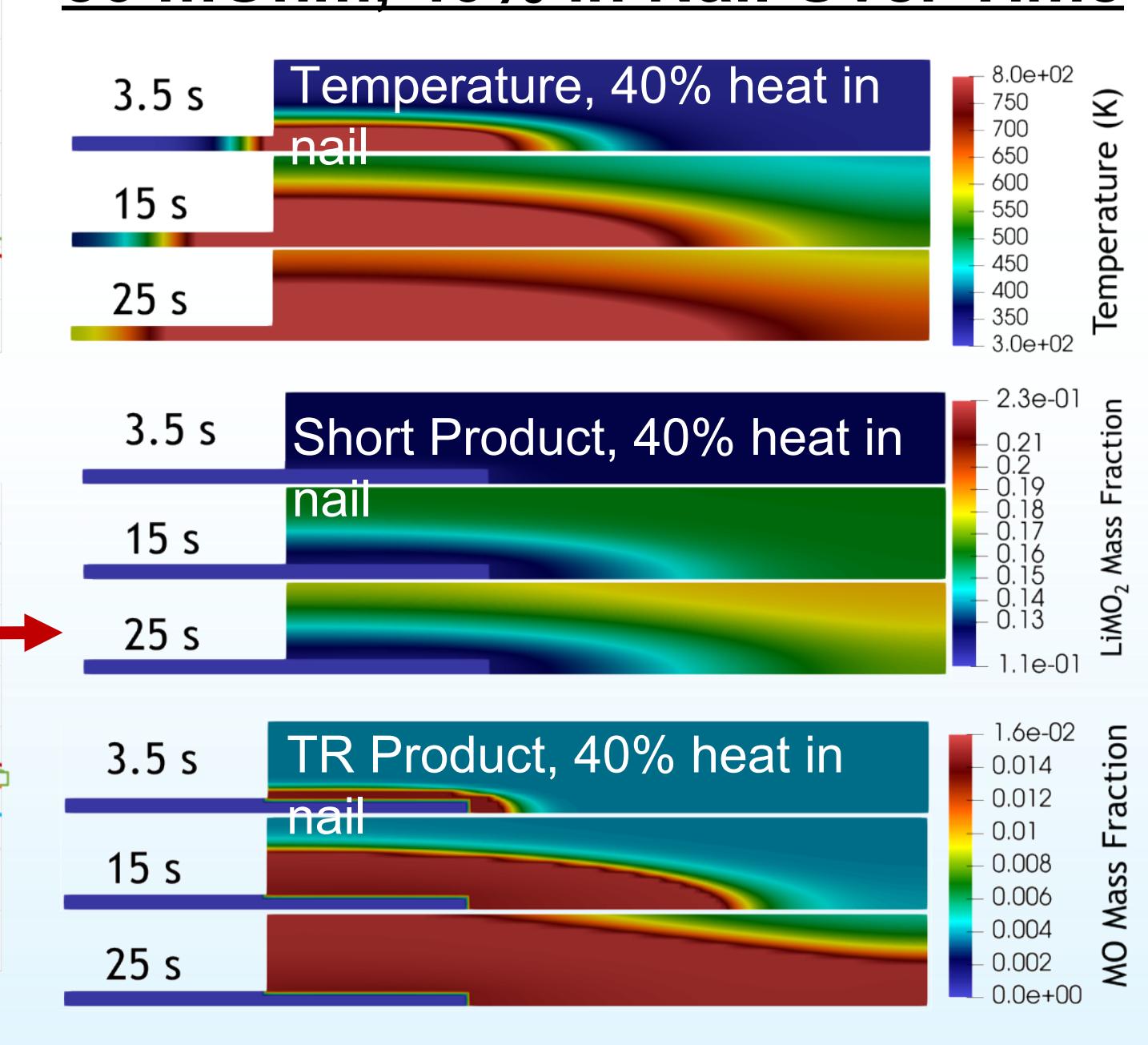
$$\text{Temperature to correlate } \frac{P}{R} = \frac{V^2}{R} = \frac{h_{eff}A(T_{eff} - T_\infty)}{h_{eff}A(T_{eff} - T_\infty)}$$



150 mΩ, Vary Nail Fraction



30 mΩ, 40% in Nail Over Time



IV: Thermal and Chemical Inhomogeneities

- 2-D axisymmetric simulations of 18650, vary % of total resistance (heat) in nail
 - Nail is hot because heat release is concentrated in small volume
 - Thermal degradation reactions dominate near hot nail

Short circuit reactions are more common near cooler periphery

Nail penetration data (1.5 Ah 18650) courtesy of Loraine Torres-Castro at Sandia National Laboratories

R. C. Shurtz, J. D. Engerer, and J. C. Hewson, *J. Electrochem. Soc.*, vol. 165, no. 16, pp. A3878-A3890, (2018), <https://dx.doi.org/10.1149/2.0541816jes>
 R. C. Shurtz, *J. Electrochem. Soc.*, vol. 167, no. 14, p. 140544, (2020), <https://doi.org/10.1149/1945-7111/abc7b4>
 R. C. Shurtz and J. C. Hewson, *J. Electrochem. Soc.*, vol. 167, no. 9, p. 090543, (2020), <https://dx.doi.org/10.1149/1945-7111/ab8fd9>
 A. M. Bates, Y. Preger, L. Torres-Castro, K. L. Harrison, S. J. Harris, and J. Hewson, *Joule*, (2022), <https://doi.org/10.1016/j.joule.2022.02.007>